

Zener Diode DE2S04300L

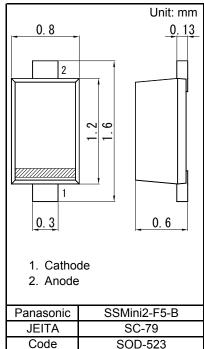
DE2S04300L Silicon epitaxial planar type

For ESD protection

- Features
- High ESD
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol 9C

Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)



Internal Connection	

■ Absolute Maximum Ratings Ta = 25	5 °C		
Parameter	Symbol	Rating	Unit
Total power dissipation ^{*1}	PT	150	mW
Electrostatic discharge *2	arge ^{*2} ESD ±30		kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm) Solder in (0.8 mm x 0.6 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

	c_3 $r_a = 25$ $C \pm 5$ C
Electrical Characteristic	$cs a = 25 \circ C \pm 3 \circ C$
Lootrigal Characteristic	aa + a = b + b + b + b + b + b + b + b + b + b

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Zener voltage *1,*2	VZ	IZ = 1 mA	4.09		4.52	V
Reverse current	IR	VR = 1 V			10.0	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		91		pF
Temperature coefficient of zener voltage *3	SZ	IZ = 1 mA		-2.1		mV/°C

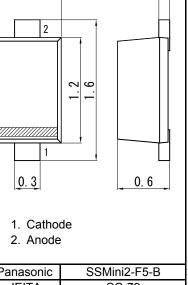
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. *1: The temperature must be controlled 25°C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2: VZ guaranted 20 ms after current flow.

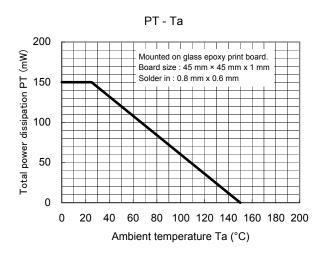
*3: Tj = 25°C to 150°C

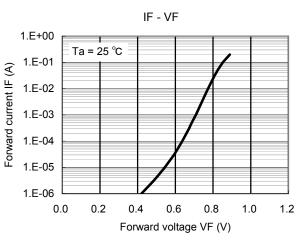




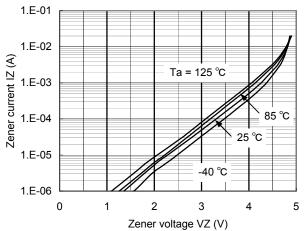
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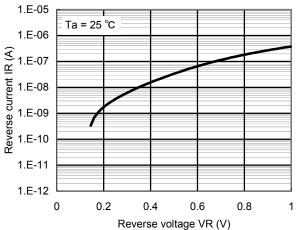


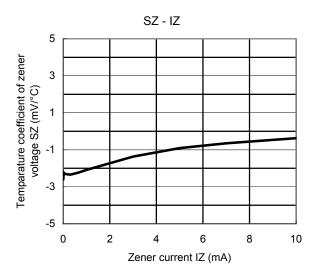










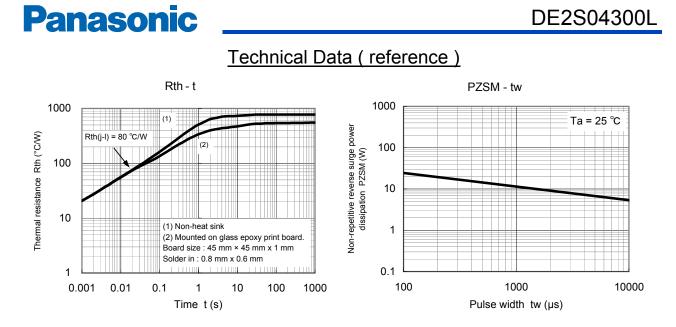


Ct - VR 120 Ta = 25 °C 100 f = 1 MHz Terminal capacitance Ct (pF) 80 60 40 20 0 0 0.5 2 1 1.5 Reverse voltage VR (V)

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Established : 2012-10-24 Revised : 2013-11-01

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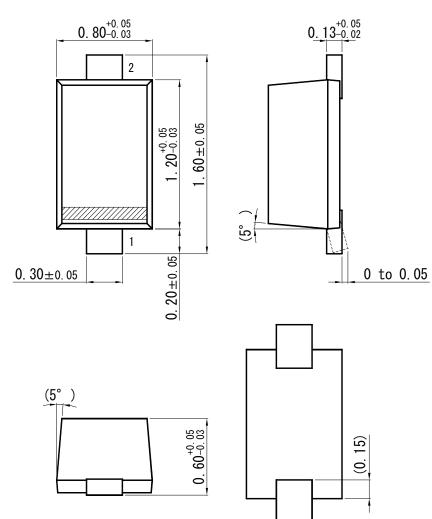




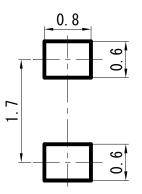
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SSMini2-F5-B

Unit: mm



Land Pattern (Reference) (Unit: mm)



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